

For: Plasma Excited Chemical Vapor Deposition Method
Silicon/Oxygen/Nitrogen-Containing-Material and Layered Assembly

RESPONSE UNDER 37 CFR § 1.116

Applicants respectfully submit the following amendments and remarks in response to Examiner's Office Action dated November 4, 2009, which Action is made final. Applicants respectfully request that these amendments and remarks be entered pursuant to the provisions of 37 CFR § 1.116, and respectfully request reconsideration of claims 21-36, and 38.